

Attorney's Docket No. 9180-12

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PATENT
11040 U.S. PTO
10/044387
01/11/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Curtis Grant Jones et al;

Serial No.: ~~not assigned yet~~ 10/044387

Filed: ~~concurrently herewith~~ 1-11-02

For: ELECTROPLATING METHODS INCLUDING MAINTAINING A DETERMINED
ELECTROPLATING VOLTAGE AND RELATED SYSTEMS

Date: January 11, 2002

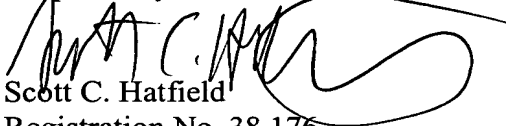
Box Patent Application
Commissioner for Patents
Washington, DC 20231

INFORMATION DISCLOSURE STATEMENT

Sir:

Attached is a list of documents on form PTO-1449 together with a copy of each identified document. It is requested that these documents be considered by the Examiner and officially made of record in accordance with the provisions of 37 C.F.R. § 1.97 and Section 609 of the MPEP. The Commissioner is hereby authorized to charge any additional fee, which may be required, or credit any refund, to our Deposit Account No. 50-0220.

Respectfully submitted,


Scott C. Hatfield
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20792

PATENT TRADEMARK OFFICE

Tel (919) 854-1400

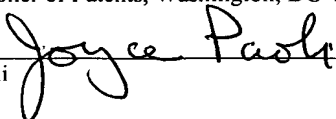
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Joyce Paoli



INFORMATION DISCLOSURE STATEMENT BY APPLICANT

Sheet	1	of	1
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Application Number	not yet assigned
Filing Date	concurrently herewith
First Named Inventor	Curtis Grant Jones
Group Art Unit	
Examiner Name	not yet assigned
Attorney Docket Number	9180-12

U.S. PTO
10/044387
01/11/02

[illegible][illegible]

OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published	T
	3.	Solomon " <i>Providing High Density and Performance for Chip-to System Interconnection</i> " Advanced Packaging (November 2001) pp 19-28	
	4.	Yung et al: " <i>Flip-Chip Process Utilizing Electroplated Solder Joints</i> "; Proceedings of the Technical Conference, (Sep. 10-12, 1990) International Electronics Packaging Conference Marlborough, Massachusetts pp1065-1073	
Examiner Signature			Date Considered

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.